Please add the following new claims:

-- 33. A method of manufacturing a custom-made liquid crystal display having a desired display area, comprising the steps of:

a) providing a finished liquid crystal display having a finished display area larger than said desired area by an excess area, the finished display having a pair of plates spaced apart in mutual parallelism to bound a space, the plates having peripheral edge regions bounding the finished area, the finished display further having a liquid crystal contained in the space and extending to all the peripheral edge regions, and a seal for sealing the peripheral edge regions to resist flow of the liquid crystal out of the space past any of the peripheral edge regions; and

b) removing the excess area from the finished area to obtain the desired area of the custom-made display.

34. The method of claim 33, wherein the removing step is performed by scoring the plates along respective grooves aligned with each other, and by fracturing both plates along the respective grooves.

35. The method of claim 34, wherein the scoring step is performed by simultaneously scoring both plates.

36. The method of claim 34, wherein the fracturing step is performed by simultaneously fracturing both plates.

37. The method of claim 34, wherein the scoring and fracturing steps are alternatingly performed by scoring and fracturing one of the plates prior to scoring and fracturing the other of the plates.

38. The method of claim 34, wherein the fracturing step is performed by positioning a respective groove in alignment with a raised projection, and by applying pressure against the excess area.

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39. The method of claim 38, wherein the positioning step is performed by positioning a first polarizer between a viewer and the plates, and a second polarizer between the plates and a source of radiation.

40. The method of claim 33, wherein the removing step is performed by directing toward the plates a laser beam having an energy level sufficient to pierce through the plates, and by performing a relative movement between the plates and the laser beam to cut the plates along a cutting line.

41. The method of claim 33; and further comprising the step of reducing a viscosity characteristic of the liquid crystal prior to performing the removing step.

42. The method of claim 41, wherein the reducing step is performed by reducing a temperature of the liquid crystal to a freezing temperature, and wherein the removing step is performed by machining the plates.

43. The method of claim 33, wherein the removing step is accompanied by exposing unsealed edges of the plates; and further comprising the step of re-sealing the unsealed edges.

44. The method of claim 43, wherein the re-sealing step is performed by thermally fusing the unsealed edges together.

45. The method of claim 33, wherein the plates have polarizing layers on external surfaces of the plates; and further comprising the step of peeling a strip of at least one of the polarizing layers off a respective plate prior to performing the removing step.

46. The method of claim 45, wherein the removing step is performed by forming a cutting line through the plates, and wherein the peeling step includes forming two peel lines at opposite sides of the cutting line, and peeling said at least one polarizing layer between the peel lines.

47. The method of claim 33, wherein the plates have conductive layers on internal surfaces of the plates, and driver connections on at least one of the plates for energizing the conductive layers; and further comprising the step of cutting through the conductive layers and at least one of the driver connections connected to the excess area.

48. The method of claim 47, wherein the step of cutting said at least one driver connection is performed prior to the removing step.

49. The method of claim 43; and further comprising the step of removing air voids within the liquid crystal, after the removal step has been performed but before performing the re-sealing step, by applying pressure against one of the plates.

50. The method of claim 33, wherein the removal step is performed by cutting the plates along a direction perpendicular to the plates.